

S/N 09/483,881

SEP 19 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. AHN et al.

Examiner: Ha Nguyen

Serial No.: 09/483,881

Group Art Unit: 2812

Filed: January 18, 2000

Docket: 303.672US1

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

#10 JDS
Kilungan
9/28/02
PATENT

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents

Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. § 1.17(p). Please charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

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Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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Date

16 Sept 2002

By

Timothy B. Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 16 day of September, 2002.

Name

Tina Kohut

Signature

2/16/02

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